

FORM PTO-1449 (REV. 7-80)	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. 30022/US/3	APPLICATION NO. 10/675,969 Not Yet Assigned
INFORMATION DISCLOSURE STATEMENT (Use several sheets if necessary)		APPLICANT(S) Sion C. Quinlan and Tim J. Bales	
		FILING DATE Concurrently herewith	GROUP ART UNIT 2811 not yet assigned J. Im

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
Jm2	AA	5,975,958	11-02-99	Weidler	439	620	
	AB	6,023,202	02-08-00	Hill	333	24	
	AC	6,109,971	08-29-00	Vadlakonda	439	620	
	AD	6,124,756	09-26-00	Yaklin et al.	327	564	
	AE	6,147,542	11-14-00	Yaklin	327	344	
	AF	6,249,171 B1	06-19-01	Yaklin et al.	327	382	
↓	AG	6,021,499	02/01/00	Aleshi	713	300	

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
Jm2	AH	00/45420	08/03/00	WO				
↓	AI	0 801 468 A2	10/15/97	EP				

OTHER PRIOR ART (Including Author, Title, Date, Pertinent Pages, Etc.)

Jm2	AJ	Al-sarawi, Said F., "Wire Bonded Stacked Chips," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website "http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node35," January 25, 2002, pp. 1-2
	AK	Al-sarawi, Said F., "Blind Castellation Interconnection," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website "http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node44," January 25, 2002, p. 1
	AL	Al-sarawi, Said F., "Silicon Efficiency," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website "http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node20," January 25, 2002, pp. 1-2
	AM	Al-sarawi, Said F., "Delay," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website "http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node22," January 25, 2002, p. 1
↓	AN	Al-sarawi, Said F., "Noise," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website "http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node23," January 25, 2002, p. 1

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Jmz	AO	Al-sarawi, Said F., "Power Consumption," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node24 ," January 25, 2002, p. 1			
	AP	Al-sarawi, Said F., "Speed," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website "http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node25," January 25, 2002, p. 1			
	AQ	Al-sarawi, Said F., "Interconnect Capacity," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website "http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node26," January 25, 2002, pp. 1-2			
	AR	Al-sarawi, Said F., "Interconnection Capacity Between Packaging Levels," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website "http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node27," January 25, 2002, p. 1			
	AS	Al-sarawi, Said F., "Stacked Tape Carrier," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node30 ," January 25, 2002, p. 1			
	AT	Al-sarawi, Said F., "Solder Edge Conductors," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node31 ," January 25, 2002, pp. 1-2			
	AU	Al-sarawi, Said F., "Thin Film Conductors on Face-of-a-Cube," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node32 ," January 25, 2002, pp. 1-2			
	AV	Al-sarawi, Said F., "An Interconnection Substrate Soldered to the Cube Face," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node33 ," January 25, 2002, pp. 1-2			
	AW	Al-sarawi, Said F., "Folded Flex Circuits," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node34 ," January 25, 2002, p. 1			
	AX	Al-sarawi, Said F., "Area Interconnection Between Stacked ICs," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node36 ," January 25, 2002, p. 1			
✓	AY	Al-sarawi, Said F., "Flip-chip Bonded Stacked Chips Without Spacers," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node37 ," January 25, 2002, p. 1			

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Jm2	AZ	Al-sarawi, Said F., "Flip-chip Bonded Stacked Chips With Spacers," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node38 ," January 25, 2002, p. 1			
	BA	Al-sarawi, Said F., "Microbridge Springs and Thermomigration Vias," Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March, 1997, obtained from website "http://www.eleceng.adelaide.edu.au/Personal/alsarawi/Packaging/node39," January 25, 2002, p. 1			
	BB	Agere Systems – About 1394, "1394 – The High-Speed Serial Interface for All the Right Reasons/1394 Driver Support," obtained from website http://www.agree.com/1394/about.html ," January 25, 2002, p. 1			
	BC	Press Release Tuesday October 17, 2000, "Lucent Technologies introduces low-power IEEE-1394A chip for high-speed connection between PCs and consumer electronic devices," obtained from website http://www.lucent.com/press/1000/001017.mea.html ," January 25, 2002, pp. 1-3			
	BD	1394 Trade Association: Technology, "1394 Technology," obtained from website http://www.1394ta.org/Technology/ ," January 25, 2002, p. 1			
	BE	1394 Trade Association: Technology, "An Introduction to the Instrument and Industrial Control Protocol," obtained at website http://www.1394ta.org/Download/Technology/iicpPaper2.pdf ," January 25, 2002, 6 pages			
	BF	Apple Computer, Inc., "Firewire Technology Fact Sheet," obtained at website "http://a772.g.akamai.net/7/772/51/f7f756ae8e5bf0/www.apple.com/firewire/pdf/FireWireFS-b.pdf", March 13, 2002, pp. 1-4			
	BG	McMunn, Lee James, "The Physical Layer," obtained at website "http://www.awstevenson.demon.co.uk/SYSNOTES/physic.htm," March 12, 2002, pp. 1-2			
	BH	Willis, P. J., "Communication Protocols," obtained at website "http://www.maths.bath.ac.uk/~pjw/NOTES/networks/chapter2_6.html," August 17, 2001, p. 1			
	BI	Willis, P. J., "The OSI Model," obtained at website "http://www.maths.bath.ac.uk/~pjw/NOTES/networks/sections2_6_1.html," August 17, 2001, p.1			
	BJ	Willis, P. J., "Physical Layer," obtained at website "http://www.maths.bath.ac.uk/~pjw/NOTES/networks/subsection2_6_1_1.html," August 17, 2001, p. 1			
	BK	Willis, P. J., "Data Link Layer," obtained at website "http://www.maths.bath.ac.uk/~pjw/NOTES/networks/subsection2_6_1_2.html," August 17, 2001, p.1			
	BL	Willis, P. J., "Network Layer," obtained at website "http://www.maths.bath.ac.uk/~pjw/NOTES/networks/subsection2_6_1_3.html," August 17, 2001, p.1			
	BM	Willis, P. J., "The Physical Layer," obtained at website "http://www.maths.bath.ac.uk/~pjw/NOTES/networks/section2_7_1.html," August 17, 2001, pp. 1-2			
	BN	Willis, P. J., "The Datalink Layer," obtained at website "http://www.maths.bath.ac.uk/~pjw/NOTES/networks/section2_7_2.html," August 17, 2001, pp. 1-2			

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Jn2	BO	Embedded Systems Programming, "Fundamentals of Firewire," obtained at website "http://www.embedded.com/1999/9906/9906feat2.htm," August 28, 2001, pp. 1-14			
↓	BP	Microprocessor and Microcomputer Standards Committee of the IEEE Computer Society, "P1394a Draft Standard for a High Performance Serial Bus (Supplement)," The Institute of Electrical and Electronics Engineers, Inc., June 30, 1999, pp.1-27			
↓	BQ	Lucent Technologies, Inc., "IEEE 1394 Isolation," Application Note, November 1998, obtained at website "http://www.agere.com/1394/docs/AP98074-01.pdf," pp. 1-16			
EXAMINER		Junghee Jm		DATE CONSIDERED 4/15/2006	
* EXAMINER: Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant(s).					

FORM PTO-1449 (REV. 7-80)		U.S. DEPARTMENT OF COMMERCE *PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. 500986.04		APPLICATION NO. 10/675,965	
INFORMATION DISCLOSURE STATEMENT <small>(Use several sheets if necessary)</small>				APPLICANT(S) Sion C. Quinlan and Tim J. Bales			
				FILING DATE September 30, 2003		GROUP ART UNIT 2811 J. Im	

U.S. PATENT DOCUMENTS							
*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
Jmz	AA	6,922,341 B2	07/26/05	Quinlan et al.	361	734	
	AB						
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	AH						
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FOREIGN PATENT DOCUMENTS								
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
	AK							
	AL							
	AM							
	AN							
	AO							

OTHER PRIOR ART <small>(Including Author, Title, Date, Pertinent Pages, Etc.)</small>		
	AP	
	AQ	
	AR	

EXAMINER <i>[Signature]</i>	DATE CONSIDERED <i>4/15/2006</i>
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PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
500986.04APPLICATION NO.
10/675,965

APPLICANT(S)

Sion C. Quinlan and Tim J. Bales

FILING DATE

September 30, 2003

GROUP ART UNIT

2811

J. Im

INFORMATION DISCLOSURE STATEMENT

(Use several sheets if necessary)

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
Jm2	AA	US-2003/0122240	07/03/03	Lin et al.	257	686	
	AB						
	AC						
	AD						
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	AG						
	AH						
	AI						
	AJ						

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		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
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	AL							
	AM							
	AN							
	AO							

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EXAMINER

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DATE CONSIDERED

4/15/2006

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